

**Supplementary Materials:  
Analysis of Nanowire pn-Junction with Combined  
Current–Voltage, Electron-Beam-Induced Current,  
Cathodoluminescence, and Electron Holography  
Characterization**

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## S1. Nanowire Growth

Core-shell nanowire arrays were grown by the vapor-liquid solid (VLS) method on p-type GaAs (111)B substrates in a low pressure metal-organic vapor phase epitaxy (MOVPE) system with a total flow of 13 l/min using hydrogen (H<sub>2</sub>) as carrier gas. An array of circular Au discs forming a square pattern of Au catalyst particles with a pitch of 500nm was defined on the surface by nano imprint lithography (NIL). SiN<sub>x</sub> growth mask was included for pattern preservation during growth.

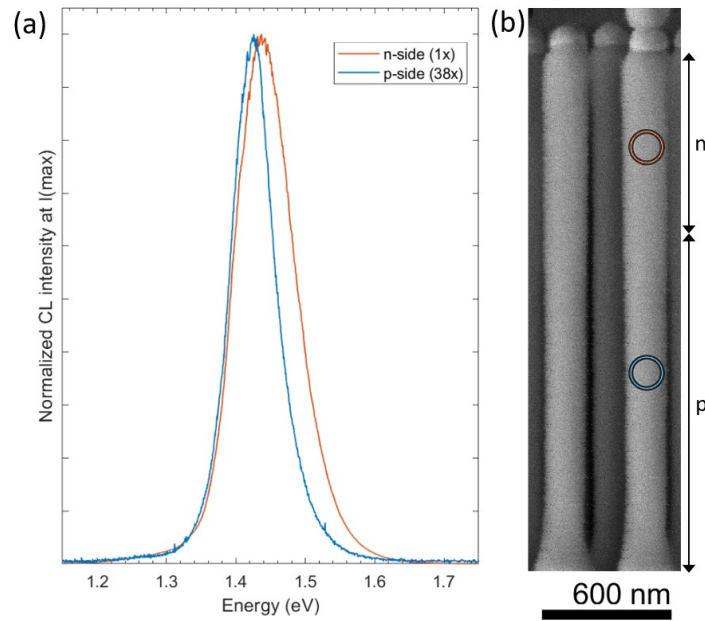
The reactor was first heated up to 375 °C under arsine mixture (AsH<sub>3</sub>/H<sub>2</sub>) with arsine molar fraction of  $7.69 \times 10^{-4}$ . Then trimethylgallium (TMGa) was introduced to the reactor for 90 s for prebake nucleation of GaAs. Subsequently, the temperature was raised to 650 °C for a 5 min annealing under AsH<sub>3</sub>/H<sub>2</sub> mixture with arsine molar fraction of  $1.15 \times 10^{-3}$ , after which the temperature was lowered to 400 °C and nanowire growth started with a 60 s p-GaAs nucleation under the flow of AsH<sub>3</sub>, TMGa and DEZn with molar fractions of  $7.69 \times 10^{-4}$ ,  $1.03 \times 10^{-4}$ , and  $5.74 \times 10^{-7}$  respectively. After p-GaAs nucleation, a 15 s Zn depletion step consisted of switching off diethylzinc (DEZn) flow and ramping AsH<sub>3</sub> flow to molar fraction of  $9.43 \times 10^{-3}$  in an attempt to deplete the Au particle of Zn. Subsequently, i-GaAs growth was continued at these molar fractions of AsH<sub>3</sub> and TMGa for another 260 s. Following i-GaAs, an n-GaAs segment was grown for 45 s by reducing AsH<sub>3</sub> and TMGa flows to molar fractions of  $2.00 \times 10^{-3}$  and  $2.23 \times 10^{-5}$ , and introducing the flow of triethyltin (TESn) with molar fraction of  $1.07 \times 10^{-5}$ . The core growth was finally completed by additional 140s of i-GaAs growth with AsH<sub>3</sub> and TMGa molar fractions as in the first i-GaAs segment growth.

After the core GaAs nanowire growth, reactor temperature and pressure were raised to 715 °C and 400 mbar, as a preparation for the shell growth. AsH<sub>3</sub> flow was increased to a molar fraction of  $1.38 \times 10^{-2}$ . The nanowires were then annealed for 5 min at 715 °C under the AsH<sub>3</sub>/H<sub>2</sub> flow mixture. The AlGaAs radial shell was then grown for 120 s by introducing TMGa and trimethylaluminum (TMAI) flows with molar fractions of  $4.37 \times 10^{-5}$  and  $1.57 \times 10^{-4}$ . Finally, to protect the AlGaAs shell from oxidation, a thin GaAs cap was grown for 120 s by switching off TMAI. The growth was ended by cooling down under AsH<sub>3</sub> flow with molar fraction of  $3.85 \times 10^{-3}$ . See Table S1 summarizing the growth steps and the key parameters.

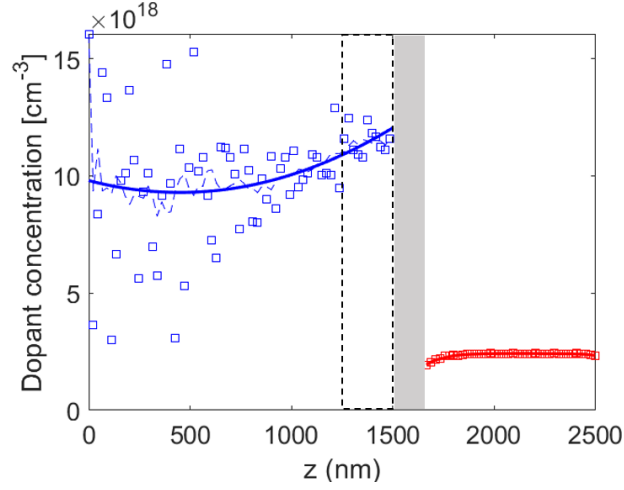
From calibration runs, we have indication that the memory effect [1] of Zn in the Au particle causes p doping throughout the first i-segment. Similarly, the second i-segment appears n doped. Thus, the growth recipe in Table S1 is intended to create a nanowire with constant p doping in the bottom part of the nanowire and constant n doping in the top part of the nanowire, with sharp transition from n to p doping.

**Table S1.** Summary of the steps and key parameters for the nanowire growth.

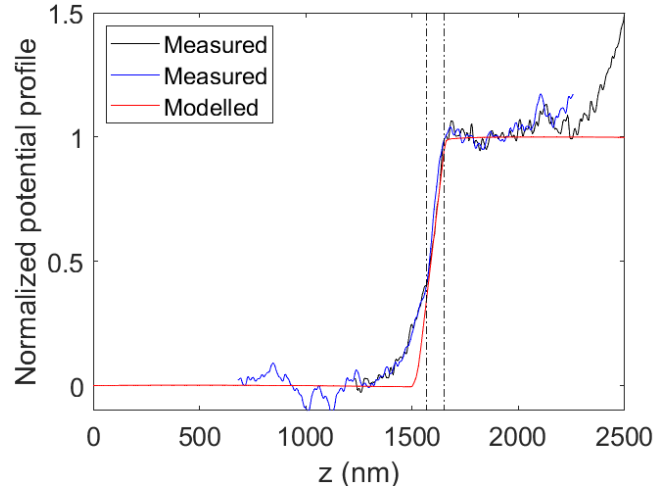
	T (C)	AsH <sub>3</sub>	TMGa	DEZn	TESn	TMAI	P (mbar)	Time (s)
Heating up under AsH <sub>3</sub>	375	7.69E-04					100	until T==375
Prebake nucleation	375	7.69E-04	2.67E-04				100	90
Ramp up T		1.15E-03					100	
Bake	650	1.15E-03					100	300
Ramp down T		1.15E-03					100	
pGaAs nucl	400	7.69E-04	1.03E-04	5.74E-07			100	60
Deplete Au of Zn	400	7.69E-04-> 9.43E-03	1.03E-04				100	15
i-GaAs	400	9.43E-03	1.03E-04				100	260
n-GaAs	400	2.00E-03	2.23E-05		1.07E-05		100	45
i-GaAs	400	9.43E-03	1.03E-04				100	140
Ramp up T, p		9.43E-03 -> 1.38E-02					100-> 400	
anneal	715	1.38E-02					400	300
AlGaAs shell	715	1.38E-02	4.37E-05			1.57E-04	400	120
GaAs cap	715	1.38E-02	4.37E-05				400	120
Cool down		3.85E-03					400	



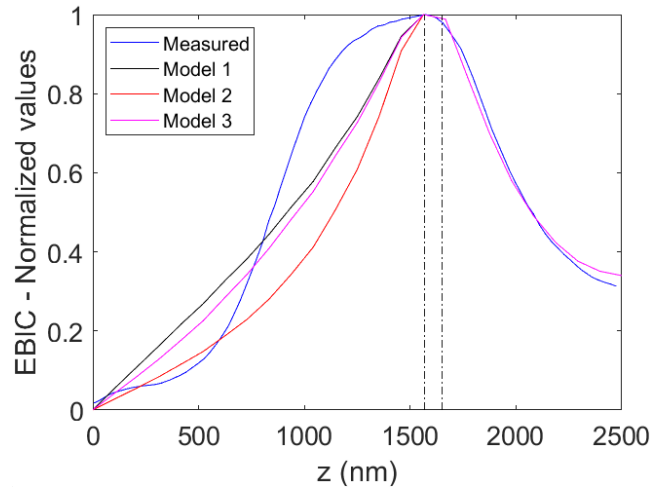
**Figure S1.** (a) CL intensity, as a function of photon energy, at approximately the middle of the n-side and p-side. Here, the peak intensity on the n-side is 38 times higher than on the p-side. (b) SEM image with the circles indicating the position of the CL measurement in (a) for the n-side (top circle) and p-side (bottom circle). The arrows with p and n mark the p-side and n-side.



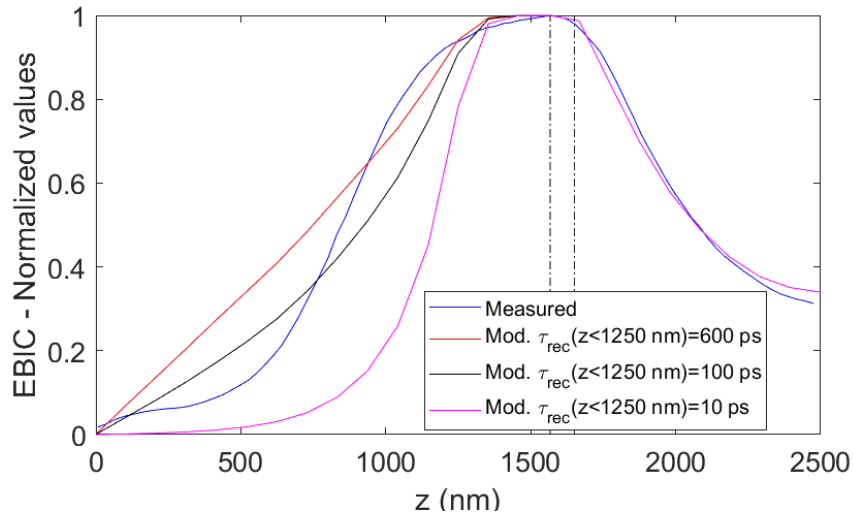
**Figure S2.** Doping concentration extracted from CL. On the n-side (red squares) we find a rather constant  $N_D \approx 2.4 \times 10^{18} \text{ cm}^{-3}$  except for a slight decline to  $1.9 \times 10^{18} \text{ cm}^{-3}$  at  $z = 1650 \text{ nm}$ . The solid red line shows a moving average, which we use as input to the drift-diffusion model. On the p-side (blue squares), we find close to the pn-junction  $N_A \approx 1.2 \times 10^{19} \text{ cm}^{-3}$  with a mild variation toward the bottom of the nanowire, with lowest value of  $N_A \approx 9.3 \times 10^{18} \text{ cm}^{-3}$ . The dashed blue line shows a moving average over 10 adjacent measurement points. The solid blue line is a second order polynomial fit, which we use in the drift diffusion model in the main text. The greyed-out region indicates the pn-junction region where free carrier density is depleted and where a strong drift field exists (see Figure 3a). The dashed region marks the  $1250 < z < 1500 \text{ nm}$  region where electron holography and EBIC indicate a drift field, as discussed in the main text.



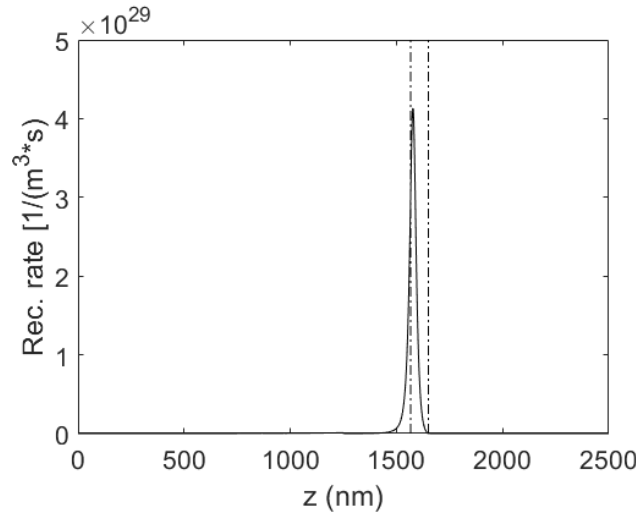
**Figure S3.** Normalized electron potential profile extracted from electron holography as a function of axial position  $z$  in a nanowire, as well as normalized values from our drift-diffusion model, here for  $V_{\text{appl}} = 0$ , that is, zero applied voltage. The measured spectra are shifted such that each of their mean value for  $z < 1250 \text{ nm}$  is zero, and after that they are normalized such that their mean value for  $1700 < z < 2000 \text{ nm}$  is equal to one. The modelled potential profile is shifted such that the value at  $z = 0$  is at zero, and then normalization is performed to the maximum value. Here, the values for  $N_A(z)$  for  $z < 1500 \text{ nm}$  from Figure S2 were used in the model. We used in the model  $N_A(z) = N_A(z_0)(1 - \text{erf}\{[z - z_0]/L_{\text{erf}}\})$  for  $1500 < z < 1650 \text{ nm}$ , with  $z_0 = 1500 \text{ nm}$  as the start of the graded region and  $L_{\text{erf}} = 20 \text{ nm}$ . Similarly as in Figure 3a, the dashed-dotted vertical lines are placed at  $z = 1567 \text{ nm}$  and at  $z = 1650 \text{ nm}$  to guide the eye.



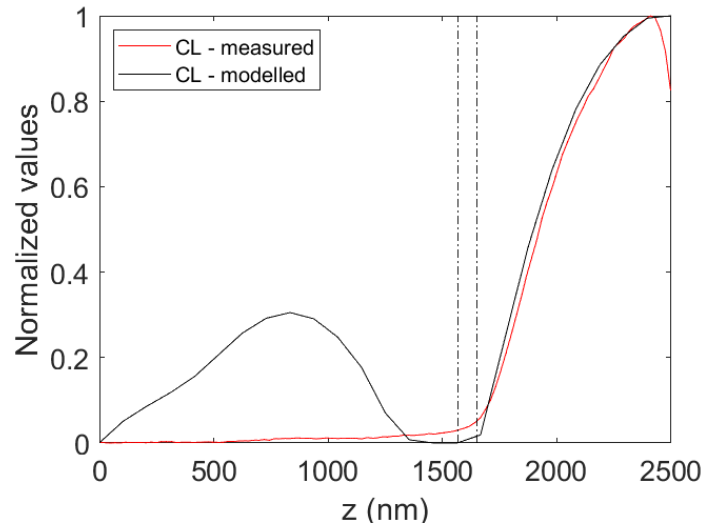
**Figure S4.** Measured and modelled EBIC. In contrast to the model in the main text, in this modelling, we use the  $N_A$  distribution that gives the modelled potential profile in Figure S3. In further contrast to the model in the main text, in Model 1 we use constant  $\tau_{\text{rec}} = 600$  ps for  $z < 1500$  nm, in Model 2  $\tau_{\text{rec}} = 100$  ps for  $z < 1500$  nm, and in Model 3  $\tau_{\text{rec}} = 100$  ps for  $z < 500$  nm,  $\tau_{\text{rec}} = 600$  ps for  $1000 < z < 1500$  nm, and for  $500 < z < 1000$  nm, we use linear variation from 100 ps to 600 ps. For all three models, the maximum modelled EBIC value is 1, within numerical uncertainty. Similarly as in Figure 3, the dashed-dotted vertical lines are placed at  $z = 1567$  nm and at  $z = 1650$  nm to guide the eye.



**Figure S5.** Measured and modelled EBIC. In contrast to the model in the main text, in the three modelled curves, we use constant  $\tau_{\text{rec}} = 600$  ps,  $\tau_{\text{rec}} = 100$  ps, and  $\tau_{\text{rec}} = 10$  ps, respectively, for  $z < 1250$  nm. For all three models, the maximum modelled EBIC value is 1, within numerical uncertainty. Similarly as in Figure 3, the dashed-dotted vertical lines are placed at  $z = 1567$  nm and at  $z = 1650$  nm to guide the eye.



**Figure S6.** Spatially resolved recombination rate from the drift-diffusion model at  $V_{\text{appl}} = 1.0$  V. Similarly as in Figure 3, the dashed-dotted vertical lines are placed at  $z = 1567$  nm and at  $z = 1650$  nm to guide the eye.



**Figure S7.** Measured CL intensity together with modelled CL intensity from the drift-diffusion model for the nanowire (see Figure 4). In the model, we assume for simplicity that the CL intensity is given by the expression for radiative recombination in a non-degenerate semiconductor:  $R_{\text{rad}} = \int_0^{2500 \text{ nm}} B (n(z)p(z) - n_i^2) dz$ , with  $n$  the electron concentration,  $p$  the hole concentration, and  $n_i$  the intrinsic carrier concentration [2]. Since we consider normalized values, the value of the radiative recombination constant  $B$  does not enter the analysis explicitly. To model the CL intensity at varying  $z$  position, we induce additional photogeneration rate at that position, similarly as in the EBIC modelling—this excess photogeneration rate induces a variation to  $n(z)$  and  $p(z)$  from the equilibrium values, giving rise to a non-zero value for  $R_{\text{rad}}$ . Similarly as in Figure 3, the dashed-dotted vertical lines are placed at  $z = 1567$  nm and at  $z = 1650$  nm to guide the eye.

## References

1. Kim, W.; Güniat, L.; Fontcuberta i Morral, A.; Piazza, V. Doping Challenges and Pathways to Industrial Scalability of III–V Nanowire Arrays. *Appl. Phys. Rev.* **2021**, *8*, 011304.
2. Sze, S.M.; Li, Y.; Ng, K.K. *Physics of Semiconductor Devices*; John Wiley & Sons: Hoboken, NJ, USA, 2021; ISBN 978-1-119-61800-3.